



PIC Packaging Services for Harsh Environments

Emma Xu, PhotonFirst, 2026

PhotonFirst Technologies

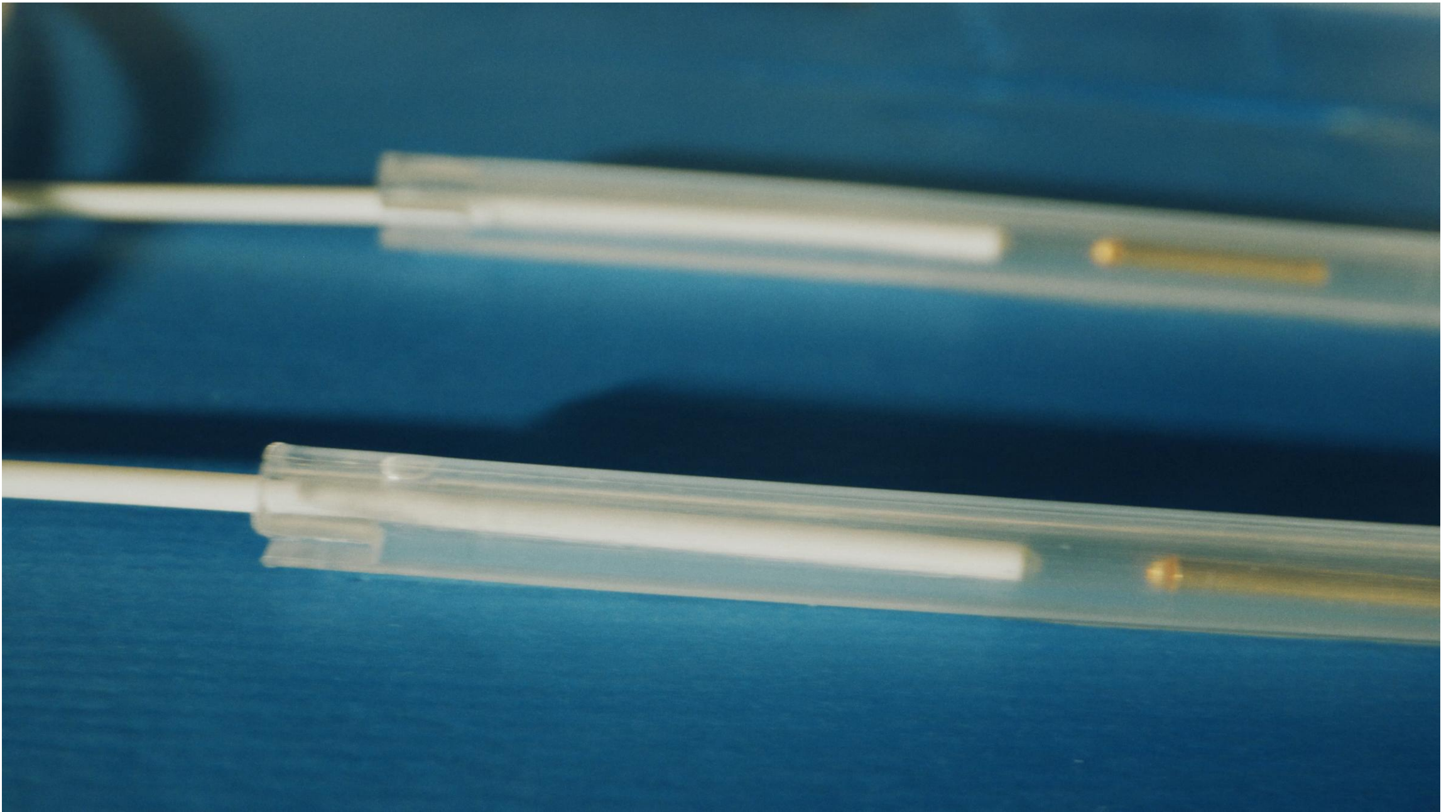
20 years experience in PIC Packaging



Headquartered in Alkmaar, team of +40 FTE

- ISO9001 certified
- DO-160 & MIL-STD-883 product development experience
- Specialization in PIC Packaging for Aero & Defense
- 500m² Cleanroom

We enable your PICs to be
deployed in **challenging**
conditions, so that you can
focus on your application



PICs in data center vs. **PICs in space**

in space, they need to survive all kinds of harsh conditions and perturbations



The challenges:

- Vibrations & shock
- Extreme temperatures (swings)
- Radiation hardening
- Moisture & chemical exposure

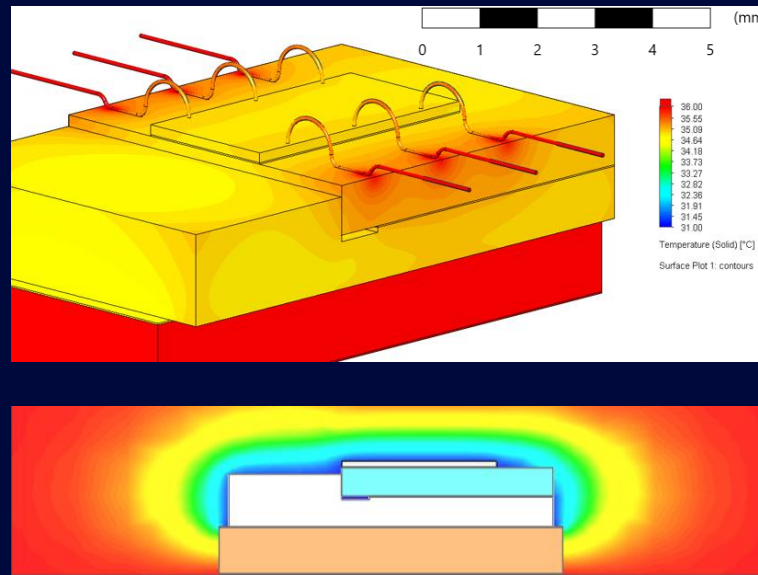
The solutions

What we do to ensure the survival of your PICs in harsh environments

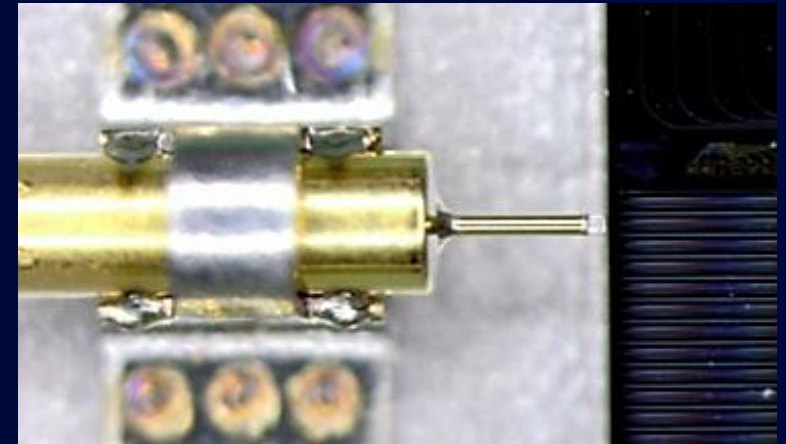
Hermetic feedthrough



Thermal management

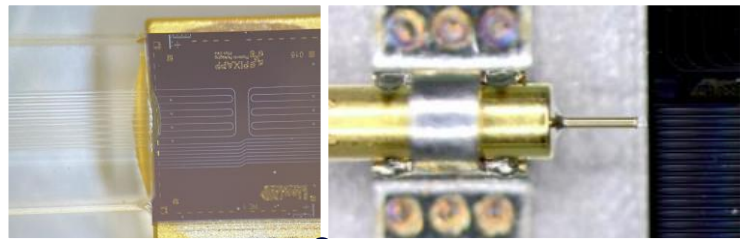
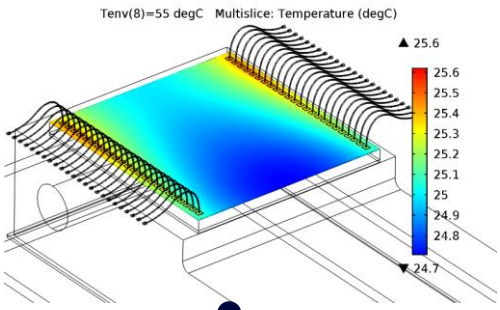


Fiber to chip connection

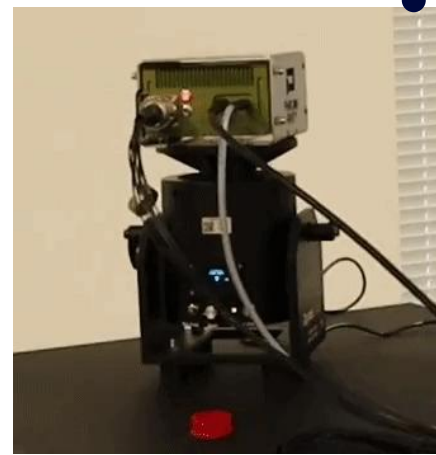
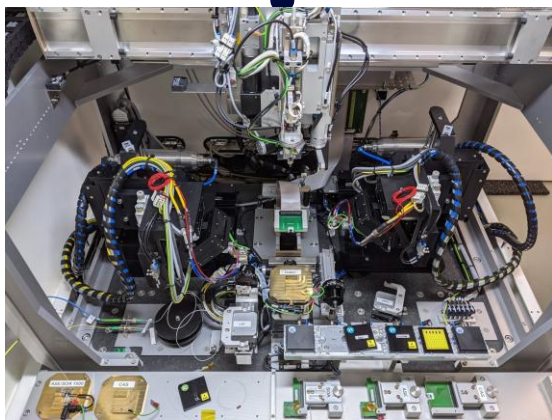


PhotonFirst offers 20+ years experience

of end-to-end PIC system development and qualification



Platform
agnostic



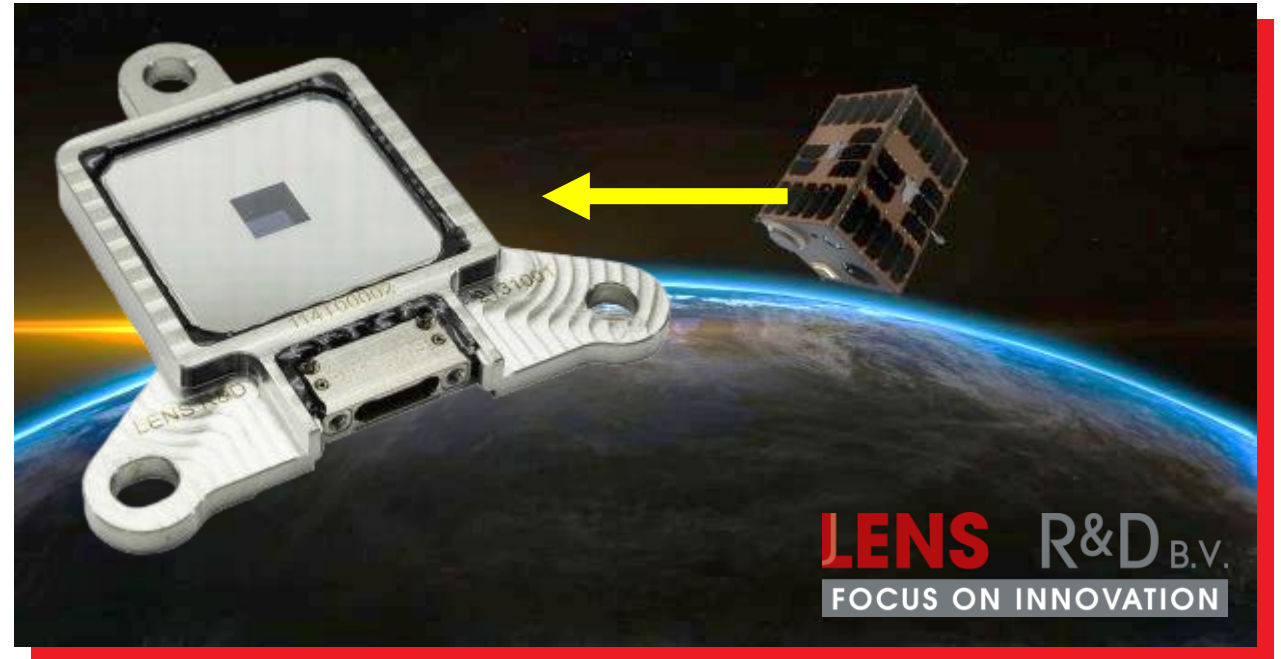
MIL-STD

PICs packaged for **harsh environments**

PICs packaged by PhotonFirst have already been deployed in various harsh environments, and produced in the **100–1000-unit** range



PhotonFirst's own FBG interrogator



Lens R&D sun sensors on satellites



contact us at

Picpackaging@photonfirst.com

Visit our website



Visit us at ECOC!
NL Pavilion, booth #1051

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